EL979979192 37298

Application Serial No. 10/004,172
PResponse to December 16, 2003 Final OA

MI22-1839

MAY 1 3 2004

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 10/004,172
Filing Date October 9, 2001
Inventor Warren M. Farnworth et al.
Assignee Micron Technology, Inc.
Group Art Unit 3729
Examiner A.D. Tugbang
Attorney's Docket No. MI22-1839
Title: Methods of Bonding Solder Balls to Bond Pads on a Substrate, and Bonding
Frames

RESPONSE TO DECEMBER 16, 2003 FINAL OFFICE ACTION PURSUANT TO 37 C.F.R. §1.116

To:

Mail Stop AF

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

From:

D. Brent Kenady

Tel. 509-624-4276; Fax 509-838-3424

Wells St. John P.S.

601 West First Avenue, Suite 1300

Spokane, WA 99201-3828

RECEIVED

MAY 2 0 2004

TECHNOLOGY CENTER R3700

Responsive to the Final Office Action dated December 16, 2003, Applicant amends and remarks as follows:

AMENDMENTS